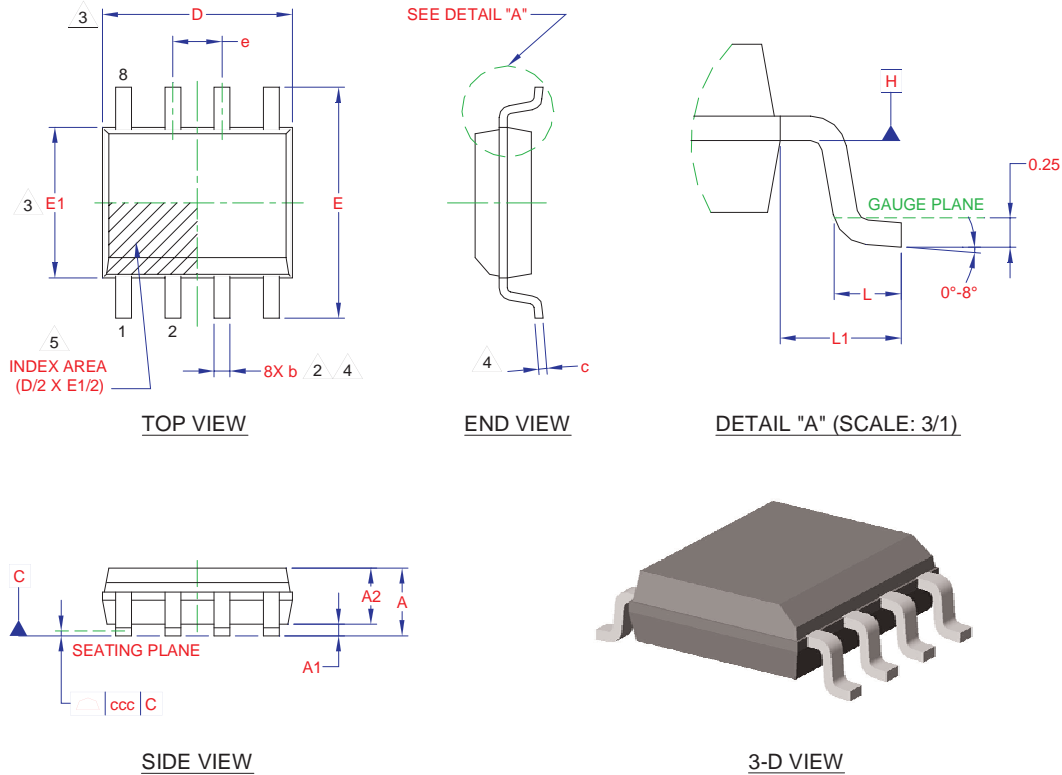


8 PIN SOIC/SOIN PACKAGE OUTLINE



	Min	Nominal	Max	Remarks
A	1.35	-	1.75	Overall Package Height
A1	0.10	-	0.25	Standoff
A2	1.25	-	1.65	Package Body Thickness
D	4.80	4.90	5.00	"X" Body Size
E	5.80	6.00	6.20	Lead Span
E1	3.80	3.90	4.00	"Y" Body Size
L	0.40	-	0.90	Lead Foot Length
L1	-	1.05 REF	-	Lead Length
b	0.31	-	0.51	Lead Width
c	0.17	-	0.25	Lead Thickness
e	-	1.27 BSC	-	Lead Pitch
ccc	-	-	0.10	Coplanarity

Notes:

1. All dimensions are in millimeters.
2. True position spread tolerance of each lead is $\pm 0.125\text{mm}$ at maximum material condition.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Maximum mold flash, protrusions or gate burrs is 0.15mm per end. Dimension "E1" does not include inter-lead flash or protrusion. Maximum inter-lead flash or protrusion is 0.25mm per side. Dimensions "D" & "E1" are determined at the datum plane "H".
4. Dimensions "b" and "c" apply to the flat section of the lead between 0.10 to 0.25mm from the lead tip.
5. Details of pin 1 identifier are optional, but must be located within the index area indicated.
6. Provided for reference only - contact your SMSC Regional Sales Office for latest information.